D3343, OCTOBER 1989

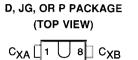
- Extremely Low Offset Voltage ... 5 μV Max
- Extremely Low Change in Offset Voltage with Temperature ... 0.003 μV/°C Typ
- Low Input Offset Current ... 30 pA Max
- A_{VD} . . . 120 dB Min
- CMRR and k_{SVR} ... 110 dB Min
- Single-Supply Operation
- Common-Mode Input Voltage Range Includes the Negative Rail
- No Noise Degradation with External Capacitors Connected to V_{DD}_

description

The ICL7652 is a precision chopper-stabilized operational amplifier manufactured using Texas Instruments Advanced LinCMOS[™] process. This process, in conjunction with unique chopper-stabilization circuitry, produces an operational amplifier whose performance matches or exceeds that of similar devices available today.

Chopper stabilization techniques make possible extremely high dc precision by continuously nulling input offset voltage even with variations in temperature, time, common-mode voltage, and supply voltage. Additionally, low-frequency noise voltage is significantly reduced. This precision, coupled with the extremely high input impedance of the CMOS input stage, makes the ICL7652 an ideal choice for low-level signal-processing applications such as strain gauges, thermocouples, and other transducer amplifiers.

The ICL7652 input common-mode range includes the negative rail, thereby providing superior performance in either single-supply or split-

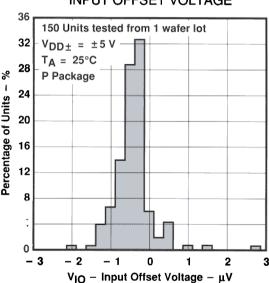




AVAILABLE OPTIONS

		PACKAGE					
	V _{IO} max	•••••==	PLASTIC				
TA	AT 25°C	OUTLINE DIP DIP					
		(D)	(JG)	(P)			
0°C to 70°C	5 μV	ICL7652D	ICL7652JG	ICL7652P			

D package is available taped and reeled. Add "R" suffix to device type (i.e., ICL7652DR).



DISTRIBUTION OF ICL7652 INPUT OFFSET VOLTAGE

supply applications, even at supply voltages as low as ± 1.9 V. The ICL7652 also features fast overload recovery time. Two external capacitors are required to operate the device; however, the on-chip chopper control circuitry is transparent to the user.

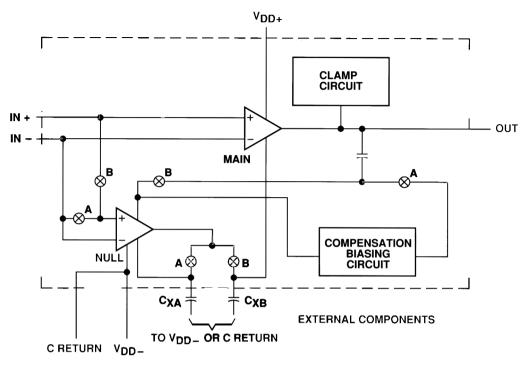
The device inputs and output are designed to withstand -100-mA surge currents without sustaining latchup. Additionally, the ICL7652 incorporates internal ESD protection circuits that prevent functional failures at voltages up to 2000 V as tested under MIL-STD-883C, Method 3015; however, care should be exercised in handling these devices, as exposure to ESD may result in degradation of the device parametric performance.

The ICL7652 is characterized for operation from 0°C to 70°C.

Advanced LinCMOS is a trademark of Texas Instruments Incorporated.



functional block diagram





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{DD+} (see Note 1) 8 V Supply voltage, V _{DD-} -8 V Differential input voltage (see Note 2) ±16 V Input voltage range, V _I (any input) ±8 V Input current, I _I (each input) ±5 mA Output current, I _O ±50 mA Duration of short-circuit current at (or below) 25°C (see Note 3) See Dissipation Rating Table Operating free-air temperature range, T _A 0°C to 70°C
· · ·
Storage temperature range –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or P package 260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: JG package

NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{DD+} and V_{DD-}.

2. Differential voltages are at the noninverting input with respect to the inverting input.

3. The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW
JG	1050 mW	8.4 mW/°C	672 mW
Р	1000 mW	8.0 mW/°C	640 mW

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V _{DD}	± 1.9	± 8	V
Common-mode input voltage, V _{IC}	V _{DD} -	V _{DD +} - 1.9	V
Operating free-air temperature, T _A	0	70	°C



electrical characteristics at specified free-air temperature, $V_{DD\pm} = \pm 5 V$ (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	ΤA [†]	MIN	ТҮР	MAX	UNIT
VIO	Input offset voltage			25°C		0.6	5	
10	input onset voltage			Full range			7.25	μV
ανιο	Temperature coefficient of input offset voltage			Full range		0.003	0.05	μV/°C
-	Input offset voltage long-term drift (see Note 4)	V _{IC} = 0,	$R_S = 50 \Omega$	25°C		0.003	0.06	μV/mo
IIO	Input offset current	• IC = 0,	118 = 50 22	25°C		2	30	pА
-10				Full range			100	
IВ	Input bias current			25°C		4	30	D A
				Full range			100	
					- 5			– pA V – V
VICR	Common-mode input voltage range	$R_{S} = 50 \Omega$		Full range	to			V
					3.1			
V _{OM +}	Maximum positive peak output voltage swing	$R_{I} = 10 k\Omega$		25°C	4.7	4.8		v
	······································			Full range	4.7			
V _{OM} –	Maximum negative peak output voltage swing	$R_{I} = 10 k\Omega$		25°C	- 4.7	- 4.9		v
				Full range	- 4.7			
A _{VD}	Large-signal differential voltage amplification	$V_{O} = \pm 4 V,$	$B_{I} = 10 k\Omega$	25°C	120	150		dB
		10 - 11,		Full range	114			u.
^f ch	Internal chopping frequency			25°C		450		Hz
CMRR	Common-mode rejection ratio	$V_{O} = 0, V_{IC}$	= V _{ICR} min,	25°C	110	140		dB
		$R_{S} = 50 \Omega$		Full range	104			
^k SVR	Supply-voltage rejection ratio ($\Delta V_{DD} + / \Delta V_{IO}$)	$V_{DD \pm} = \pm 1.9$		25°C	110	135		dB
001		V _O = 0,	$R_{S} = 50 \Omega$	Full range	104			
IDD	Supply current	$V_{O} = 0,$	No load	25°C		1.5	2.4	mA
טטי				Full range			3.5	

NOTE 4: Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at $T_A = 150^{\circ}C$ extrapolated to $T_A = 25^{\circ}C$ using the Arrhenius equation and assuming an activation energy of 0.96 eV.

operating characteristics at specified free-air temperature, $V_{DD\pm} = \pm 5 V$ (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	TAt	MIN	TYP	MAX	UNIT
SR +	Positive slew rate at unity gain	$N_{2} = \pm 2.2 M$	25°C	2	2.8		V/µs
	Tostive siew rate at unity gain	$V_{O} = \pm 2.3 V,$ - $R_{I} = 10 k\Omega,$	Full range	1.5			- ν/μs
SR – Negative slew rate at unity	Negative slew rate at unity gain		25°C	2.3	3.1		V/µs
	Negative siew rate at unity gain	C _L = 100 pF	Full range	1.8] v/μs
V _n E	Equivalent input noise voltage (see Note 5)	f = 10 Hz	25°C		94		_ nV/√Hz
	Equivalent input hoise voltage (see Note 5)	f = 1 kHz	25°C		23		<u>רוייייר</u>
	Peak-to-peak equivalent input noise voltage	f = 0 to 1 Hz	25°C		0.8		
V _{N(PP)}	reak-to-peak equivalent input hoise voitage	f = 0 to 10 Hz	25°C		2.8		- μν
In	Equivalent input noise current	f = 1 kHz	25°C		0.004		pA/√Hz
	Gain-bandwidth product	$ f = 10 \text{ kHz}, R_{L} = 10 \text{ k}\Omega, \\ C_{L} = 100 \text{ pF} $	25°C	-	1.9		MHz
<i>ø</i> m	Phase margin at unity gain	$R_{L} = 10 \text{ k}\Omega, C_{L} = 100 \text{ pF}$	25°C		48°		

[†]Full range is 0°C to 70°C.

NOTE 5: This parameter is tested on a sample basis for the ICL7652. For other test requirements, please contact the factory. This statement has no bearing on testing or nontesting of other parameters.

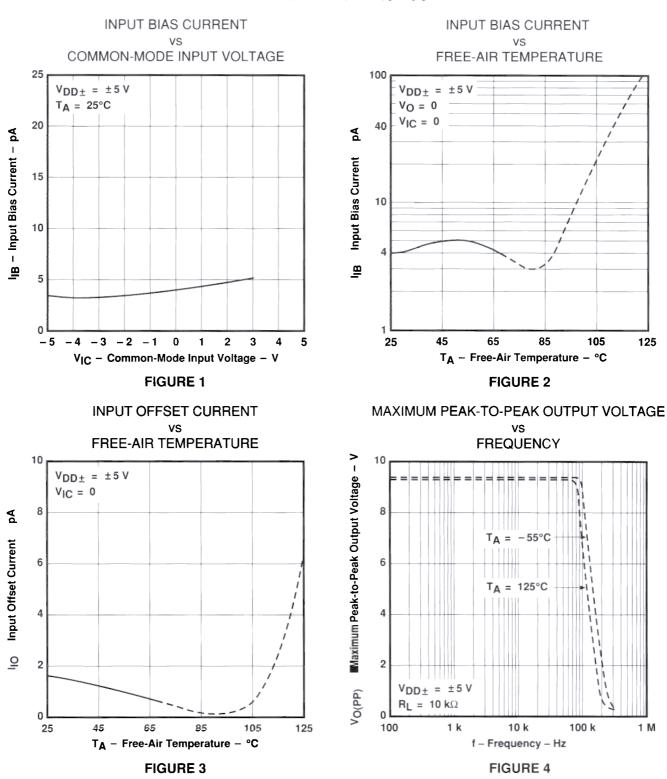


TYPICAL CHARACTERISTICS

table of graphs

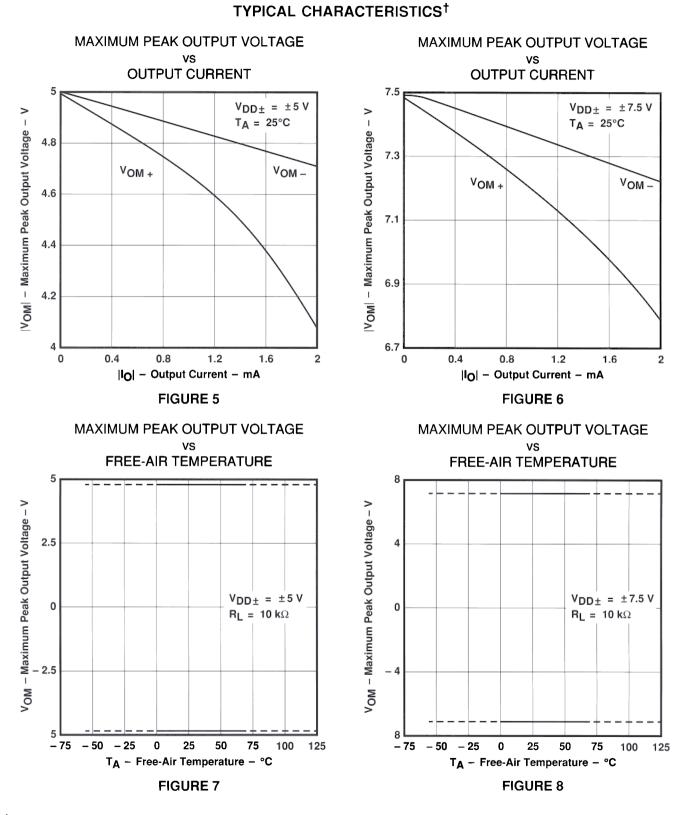
			FIGURE
lin.	Input bias current	vs Common-mode input voltage	1
lΒ	input bias current	vs Temperature	2
IIO	Input offset current	vs Temperature	3
V _{O(PP)}	Maximum peak-to-peak output voltage swing	vs Frequency	4
	Maximum pack output voltage swing	vs Output current	5, 6
VOM	Maximum peak output voltage swing	vs Temperature	7, 8
A	Differential values amplification	vs Frequency	9
A _{VD}	Differential voltage amplification	vs Temperature	10
1	Quarky surrant	vs Supply voltage	11
IDD	Supply current	vs Temperature	12
		vs Supply voltage	13
los	Short-circuit output current	vs Temperature	14
00	Olaur asta	vs Supply voltage	15
SR	Slew rate	vs Temperature	16
		Small-signal	17
	Pulse response	Large-signal	18
		vs Supply voltage	19
	Gain-bandwidth product	vs Temperature	20
Vn	Equivalent input noise voltage	vs Frequency	21
	· · · · · · · · · · · · · · · · · · ·	vs Supply voltage	22
<i>∲</i> m	Phase margin	vs Temperature	23
		vs Load capacitance	24
	Phase shift	vs Frequency	9



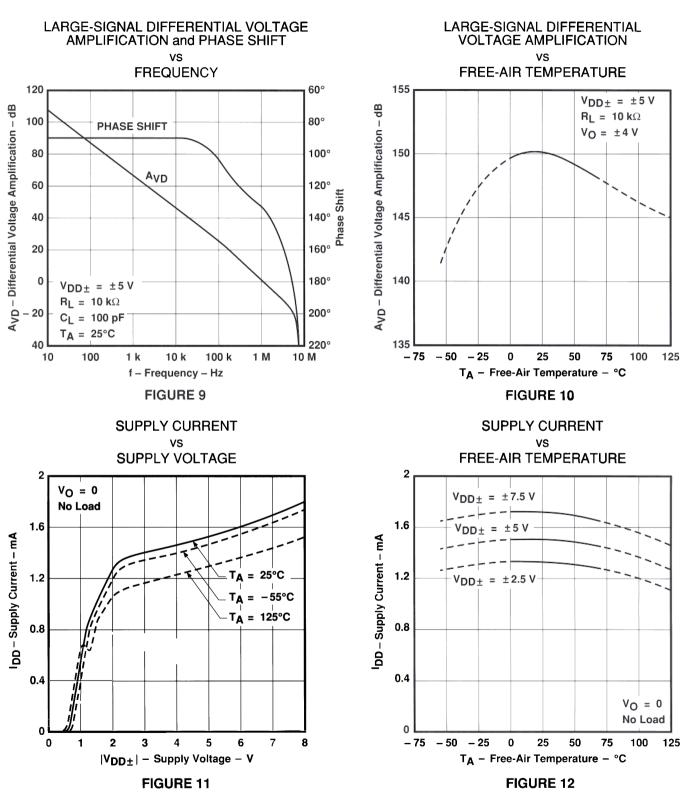


TYPICAL CHARACTERISTICS[†]



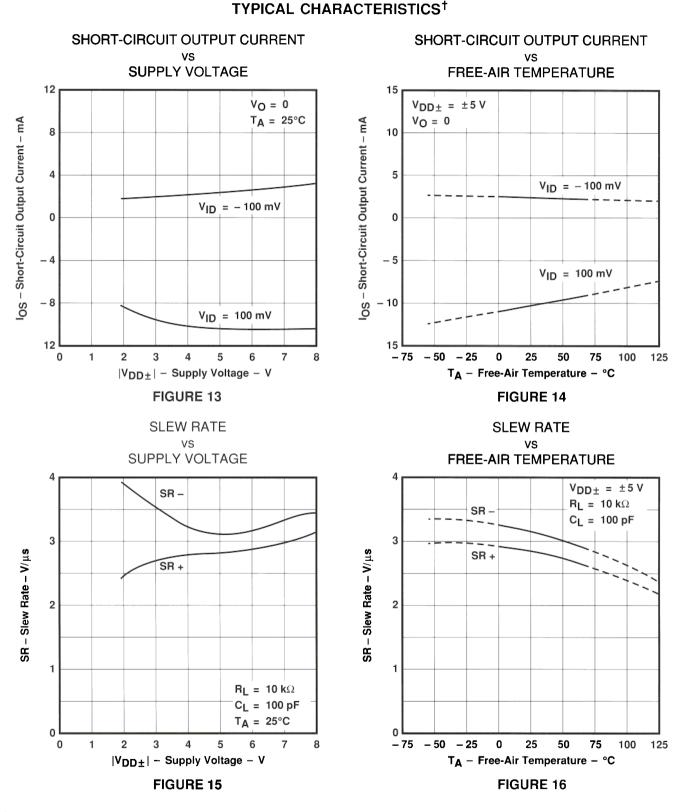




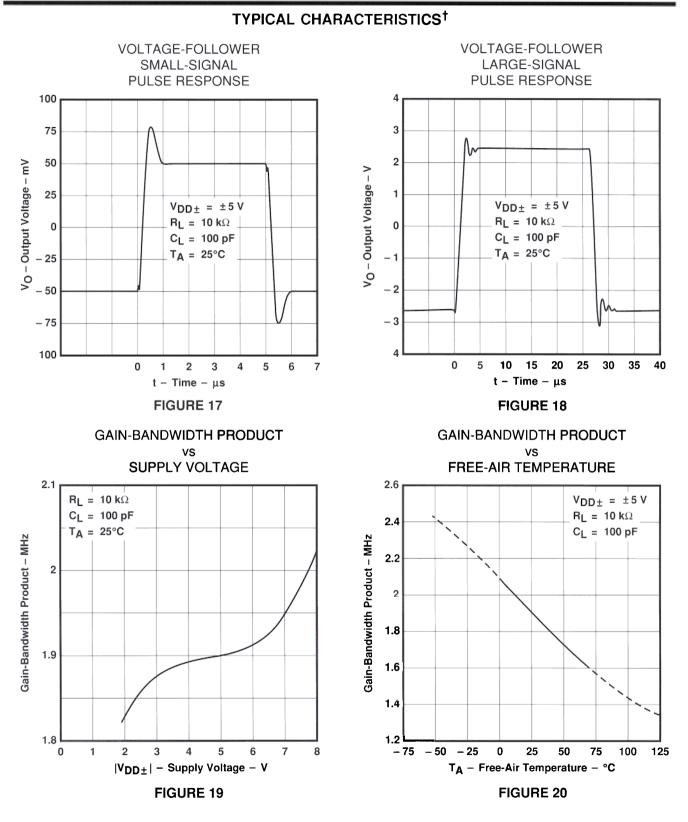


TYPICAL CHARACTERISTICS[†]

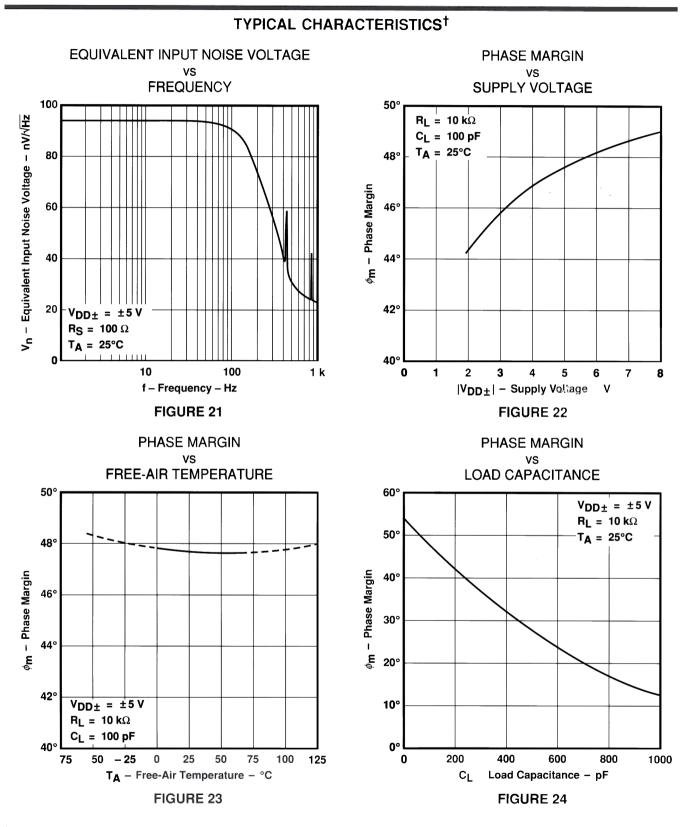












TYPICAL APPLICATION DATA

capacitor selection and placement

The two important factors to consider when selecting external capacitors C_{XA} and C_{XB} are leakage and dielectric absorption. Both factors can cause system degradation that negate the performance advantages realized by using the ICL7652.

Degradation from capacitor leakage becomes more apparent with increasing temperatures. Low-leakage capacitors and standoffs are recommended for operation at $T_A = 125$ °C. In addition, guardbands around the capacitor connections on both sides of the printed circuit board are recommended to alleviate problems caused by surface leakage on circuit boards.

Capacitors with high dielectric absorption tend to take several seconds to settle upon application of power, which directly affects input offset voltage. In applications needing fast settling of input offset voltage, it is recommended that high-quality film capacitors, such as mylar, polystyrene, or polypropylene, be used. In other applications, however, a ceramic or other low-grade capacitor may suffice.

Unlike many choppers available today, the ICL7652 is designed to function with values of C_{XA} and C_{XB} in the range of 0.1 μ F to 1 μ F without degradation to input offset voltage or input noise voltage. These capacitors should be located as close as possible to the C_{XA} and C_{XB} pins and returned to either the V_{DD-} pin or the C RETURN pin. Note that on many choppers, connecting these capacitors to the V_{DD-} pin causes degradation in noise performance, a problem that is eliminated on the ICL7652.

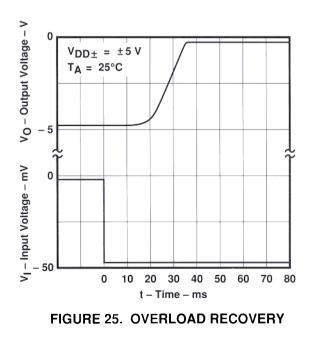
overload recovery/output clamp

When large differential input voltage conditions are applied to the ICL7652, the nulling loop attempts to prevent the output from saturating by driving C_{XA} and C_{XB} to internally-clamped voltage levels. Once the overdrive condition is removed, a period of time is required to allow the built-up charge to dissipate. This time period is defined as overload recovery time (see Figure 25). Typical overload recovery time for the ICL7652 is significantly faster than that of competitive products.

thermoelectric effects

To take advantage of the extremely low offset voltage temperature coefficient of the ICL7652, care must be taken to compensate for the thermoelectric effects present when two dissimilar metals are brought into contact with each other (such as device leads being soldered to a printed circuit board). It is not uncommon for dissimilar metal junctions to produce thermoelectric voltages in the range of several microvolts per degree Celsius (orders of magnitude greater than the 0.01- μ V/°C typical of the ICL7652).

To help minimize thermoelectric effects, careful attention should be paid to component selection and circuit board layout. Avoid the use of nonsoldered connections (such as sockets, relays, switches, etc.) in the input signal path. Cancel thermoelectric effects by duplicating the number of components and junctions in each device input. The use of low-thermoelectriccoefficient components, such as wire-wound resistors, is also beneficial.





TYPICAL APPLICATION DATA

avoiding latchup

The ICL7652 inputs and output are designed to withstand –100-mA surge currents without sustaining latchup. However, because CMOS devices are susceptible to latchup due to their inherent parasitic thyristors, techniques to reduce the chance of latchup should be used whenever possible. Internal protection diodes should not be forward biased in normal operation. Applied input and output voltages should not exceed the supply voltage by more than 300 mV. Care should be exercised when using capacitive coupling on pulse generators. Supply transients should be shunted by using decoupling capacitors (0.1 μ F typical) located across the supply rails as close to the device as possible.

The current path established if latchup occurs is usually between the supply rails and is limited only by the impedance of the power supply and the forward resistance of the parasitic thyristor. The chance of latchup occurring increases with increasing temperature and supply voltage.

electrostatic discharge protection

The ICL7652 incorporates internal ESD protection circuits that prevent functional failures at voltages at or below 2000 V. Care should be exercised in handling these devices, as exposure to ESD may result in degradation of the device parametric performance.

theory of operation

Chopper-stabilized operational amplifiers offer the best dc performance of any monolithic operational amplifier. This superior performance is the result of using two operational amplifiers – a main amplifier and a nulling amplifier – plus oscillator-controlled logic and two external capacitors to create a system that behaves as a single amplifier. With this approach, the ICL7652 achieves submicrovolt input offset voltage, submicrovolt noise voltage, and offset voltage variations with temperature in the $nV/^{\circ}C$ range.

The ICL7652 on-chip control logic produces two dominant clock phases – a nulling phase and an amplifying phase. The term "chopper-stabilized" derives from the process of switching between these two clock phases. Figure 26 shows a simplified block diagram of the ICL7652. Switches A and B are make-before-break types. During the nulling phase, switch A is closed, shorting the nulling amplifier inputs together and allowing the nulling amplifier to reduce its own input offset voltage by feeding its output signal back to an inverting input node. Simultaneously, external capacitor C_{XA} stores the nulling potential to allow the offset voltage of the amplifier to remain nulled during the amplifying phase.

During the amplifying phase, switch B is closed, connecting the output of the nulling amplifier to a noninverting input of the main amplifier. In this configuration, the input offset voltage of the main amplifier is nulled. Also, external capacitor C_{XB} stores the nulling potential to allow the offset voltage of the main amplifier to remain nulled during the next nulling phase.

This continuous chopping process allows offsetvoltage nulling during variations in time and temperature and over the common-mode input voltage range and power supply range. In addition, because the low-frequency signal path is through both the null and main amplifiers, extremely high gain is achieved.

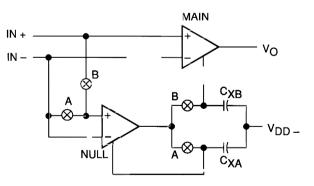


FIGURE 26. SIMPLIFIED BLOCK DIAGRAM

TYPICAL APPLICATION DATA

The low-frequency noise of a chopper amplifier depends on the magnitude of the component noise prior to chopping and the capability of the circuit to reduce this noise while chopping. The use of the Advanced LinCMOS[™] process, with its low-noise analog MOS transistors and patent-pending input stage design, significantly reduces the input noise voltage.

The primary source of nonideal operation in chopper-stabilized amplifiers is error charge from the switches. As charge imbalance accumulates on critical nodes, input offset voltage can increase, especially with increasing chopping frequency. This problem has been significantly reduced in the ICL7652 by use of a patent-pending compensation circuit and the Advanced LinCMOS[™] process.

The ICL7652 incorporates a feed-forward design that ensures continuous frequency response. Essentially, the gain magnitude of the nulling amplifier and compensation network crosses unity at the break frequency of the main amplifier. As a result, the high-frequency response of the system is the same as the frequency response of the main amplifier. This approach also ensures that the slewing characteristics remain the same during both the nulling and amplifying phases.

temperature coefficient of input offset voltage

Figure 27 shows the effects of package-induced thermal EMF. The ICL7652 can null only the offset voltage within its nulling loop. There are metal-to-metal junctions outside the nulling loop (bonding wires, solder joints, etc.) that produce EMF. In Figure 27, an ICL7652 was placed in an oven at 25°C at t = 0, biased up, and allowed to stabilize. At t = 3 min, the oven was turned on and allowed to rise in temperature to 125°C. As evidenced by the curve, the overall change in input offset voltage with temperature is much less than the specified maximum limit of 0.05 μ V/°C.

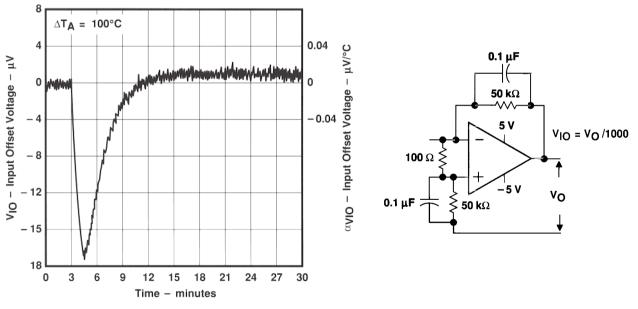


FIGURE 27. EFFECTS OF PACKAGE-INDUCED THERMAL EMF





PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
ICL7652P	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	ICL7652P
ICL7652P.A	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	ICL7652P

⁽¹⁾ **Status:** For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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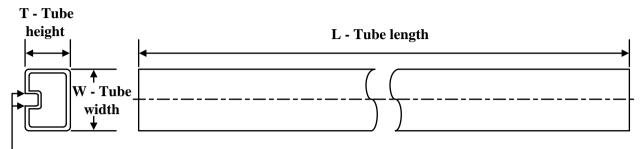
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TEXAS INSTRUMENTS

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TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
ICL7652P	Р	PDIP	8	50	506	13.97	11230	4.32
ICL7652P.A	Р	PDIP	8	50	506	13.97	11230	4.32

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